

## Data collection/ collation on the “state of the art” in Microfluidic Systems Packaging

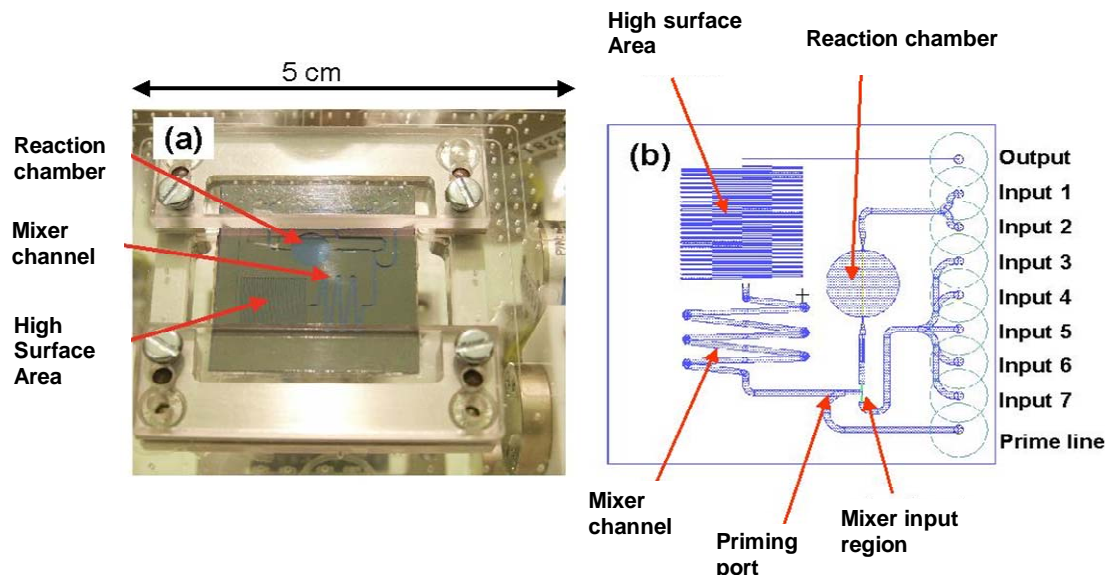
### Objective

WP4 have divided the Microsystems field into applications areas (inertial MEMS, environmental MEMS, RF MEM, MOEMS, BioMEMS and Microfluidics).

For each application area a technical working group has been formed to compile state of the art, know-how and capability information, on **Microsystems packaging solutions** (packaging, assembly, interfacing and interconnection), including:

- Failure mechanisms of microsystems packaging
- Test structures for package monitoring and package design
- Data on packaging construction and materials
- Packaging capabilities within PATENT, and externally within Europe

### Microfluidics Packaging



### Partners QinetiQ

Picture courtesy of QinetiQ

### Summary of results

Collection/ collation of data on packaging on fluidic systems

### Offer to industry

Reports and consultancy on packaging of fluidic devices

Contact A. Wilkinson ([aswilkinson@QinetiQ.com](mailto:aswilkinson@QinetiQ.com))

### Project status

Ongoing